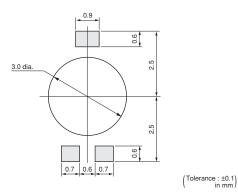
Mounting

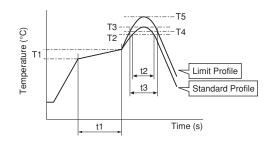
■ Land Pattern



■ Soldering Profile

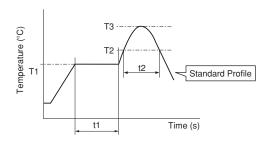
■ Reflow Soldering Profile

1. Soldering profile for lead free solder (96.5Sn/3.0Ag/0.5Cu)



	Standard Profile					Limit Profile						
Series	Pre-heating		Heating		Peak Temperature	Cycle of	Pre-heating		Heating		Peak Temperature	Cycle of
	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	(T3)	Reflow	Temp. (T1)	Time (t1)	Temp. (T4)	Time (t3)	(T5) F	Reflow
	°C	sec.	°C	sec.	°C	Time	°C	sec.	°C	sec.	°C	Time
PVZ2	150 to 180	60 to 120	220	30 to 60	245±3	2	150 to 180	60 to 120	220	30 to 60	260	2
PVA2	150 to 180	60 to 120	220	30 to 60	245±3	2	150 to 180	60 to 120	220	30 to 60	260 +5/-0	2

2. Soldering profile for Eutectic solder (63Sn/37Pb) (Limit profile: refer to 1)



	Standard Profile								
Series	Pre-he	eating	Hea	ting	Peak Temperature	Cycle of Reflow			
	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	(T3)				
	°C	sec.	°C	sec.	°C	Time			
PVZ2 PVA2	150	60 to 120	183	30	230	1			

Soldering Iron

	Standard Condition							
Series	Temperature of Soldering Iron Tip	Soldering Time	Soldering Iron Power Output	Cycle of Soldering Iron				
	°C	sec.	W	Time				
PVZ2 PVA2	350±10	3 max.	30 max.	1				